



中国认可
国际互认
检测
TESTING
CNAS L12524

Test Report

Sample Name: _____ The Integrated Circuit _____

Part Number: _____ TLC555IDR _____

Manufacturer: _____ TI _____

Customer: _____

Shenzhen Chuangxin Online Testing Service Co., Ltd.

November 01, 2024

Test Report

Customer:

Customer Address:

Sample Name: The Integrated Circuit

Part Number: TLC555IDR

Manufacturer: TI

Date Code: 2409+5

Package Type: 8-SOIC

Quantity Received: 2500 PCS

Quantity Inspected: 5 PCS

Date Received: 10/31/2024

Date Tested: 11/01/2024/10: 00 - 11/01/2024/11: 00

Issued by

(Stamp)

Tested by _____

Inspected by _____

Approved by _____

Test Items

External visual inspection

Pin correlation test

Programming test

Solderability analysis

Radiography(X-ray)

XRF test

Key functional test(KFT)

Baking

Tape and reel

Top permanency test

Internal visual inspection

SAT test

Cross section

Methods & Equipment

1.1 Test standard:

- **AS6081-2012 4.2.6.4.4**

1.2 Optical microscope:

- Equipment spec:

Optical microscope: SEZ-260 X7-X45(Due date: 07/17/2025)

1.3 X-ray flaw detector:

- Equipment spec:

X-ray flaw detector: X6600 70KV/40uA(Due date: 07/17/2025)

1.4 Datasheet Reference:

- 《TI TLC555IDR》:

<https://www.ti.com/general/docs/suppproductinfo.tsp?distId=10&gotoUrl=https%3A%2F%2Fwww.ti.com%2Flit%2Fgpn%2Ftlc555>

Analysis Summary

Radiography(X-ray):

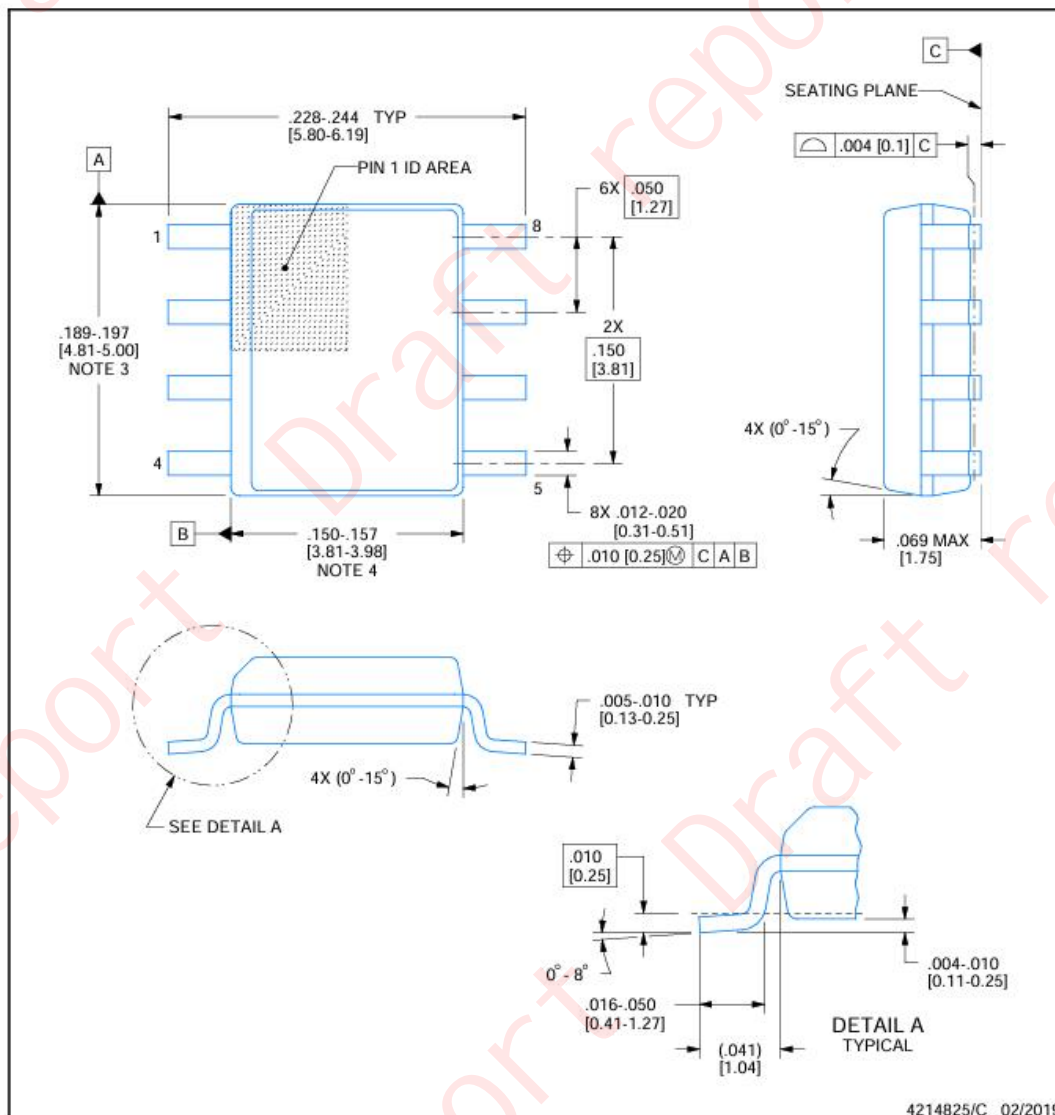
Applicable standard: **AS6081-2012 4.2.6.4.4**

X-ray inspection on 5 PCS samples(#1-#5). The 5 PCS samples have the same structure. No structure or bonding wire abnormal was found. 5 PCS samples passed X-ray inspection.

1. Device description:

The TLC555 is a monolithic timing circuit fabricated using the TI LinCMOS™ technology. The timer is fully compatible with CMOS, TTL, and MOS logic and operates at frequencies up to 2 MHz. Because of a high input impedance, this device supports smaller timing capacitors than those supported by the NE555 or LM555.

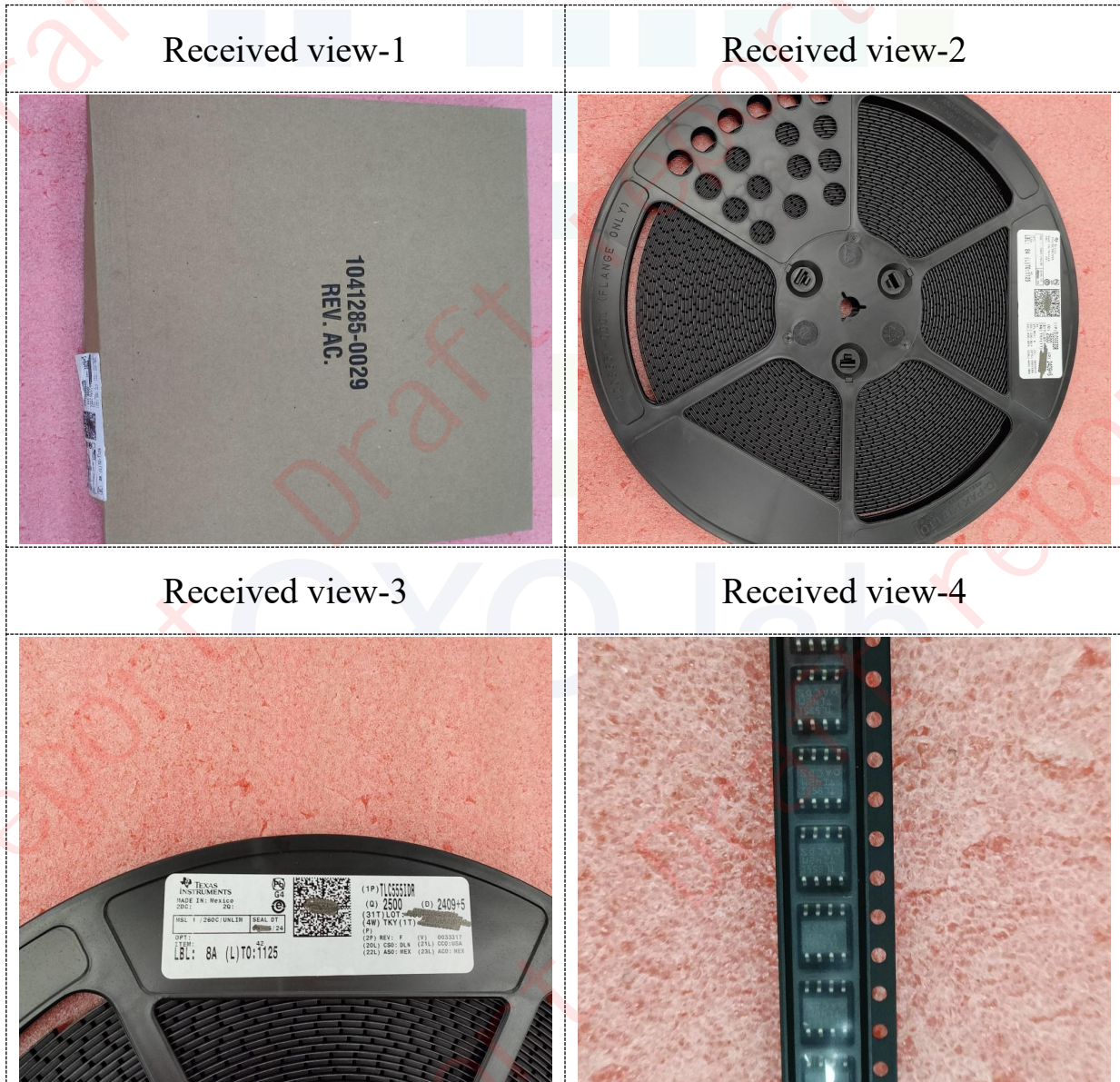
2. Package dimensions:



3. Documentation and packaging inspection:

Gross Weight	567 g	Quantity Received	2500 PCS
Number of Boxes	N/A	Full Label	Exist
Package Type	Reel	Moisture Protection	N/A
MSL	1	ESD Protection	N/A

Note: All devices contain 2500 PCS samples.



4. Radiography(X-ray):

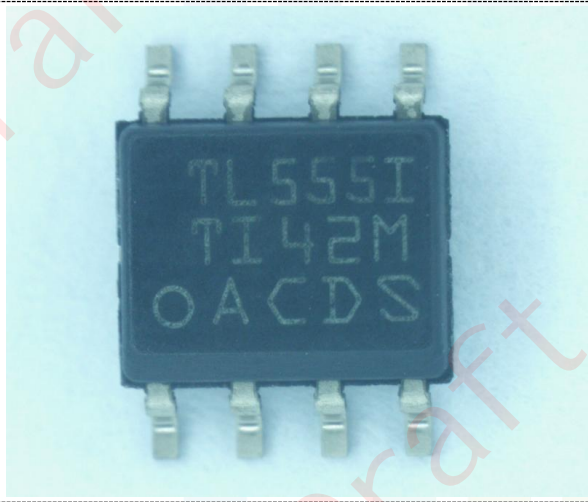
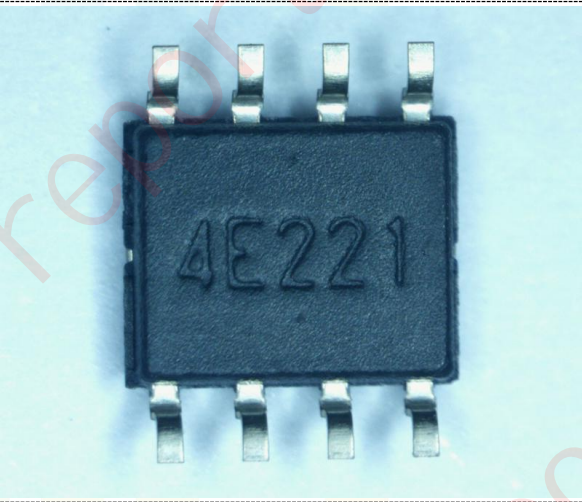
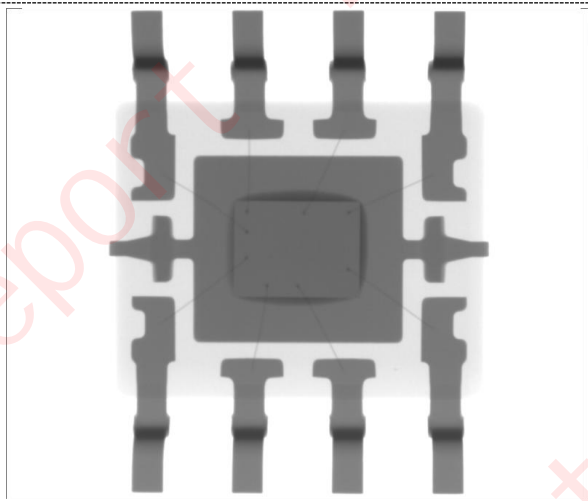
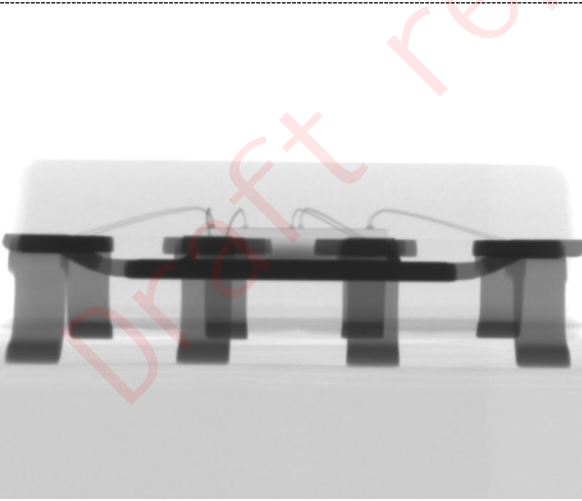
Applicable standard: AS6081-2012 4.2.6.4.4

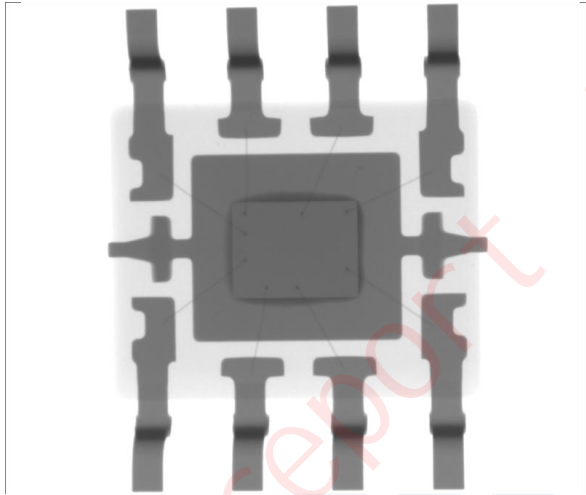
Ambient Temperature: 23.5 °C Relative Humidity: 57.3 % RH

X-ray inspection on 5 PCS samples(#1-#5). The 5 PCS samples have the same structure. No structure or bonding wire abnormal was found. 5 PCS samples passed X-ray inspection.

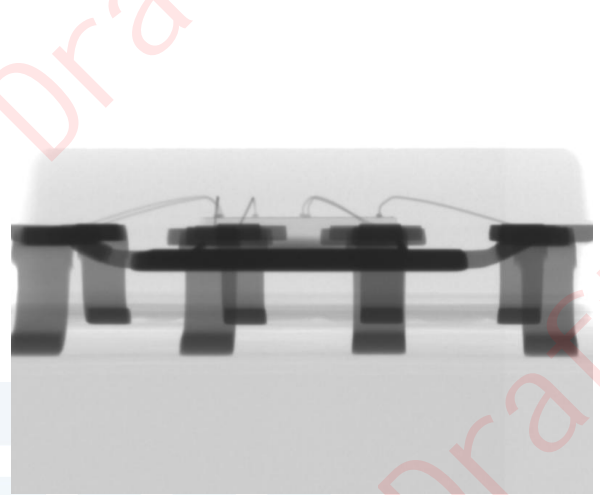
Sample No	Test Items	Result
#1-#5	Whether there are cracks, bonding tilts, or anomalies outside the bonding range in the internal wafer	Pass
	Whether the internal bonding wire is broken, crossed wire, radian exceeding the standard, and solder joint is abnormal	Pass
	Check whether the internal lead rack and substrate structure are abnormal	Pass
	Whether the void at the internal bonding interface is abnormal. Whether the bonding material is separated from the main body, and the accumulation of the bonding material is too high	Pass
	Whether the internal wafer, bonding wire, bonding mode, material, lead frame, substrate structure and internal bonding are consistent when multiple samples are tested	Pass

	<p>Side view inside the climbing height of the bonding material, the arc of the bonding wire, the distance between the bonding wire and the top, and the first and second solder joints are abnormal</p>	<p>Pass</p>
	<p>Whether there are attached or free particles in the sample exceeding 0.025mm, whether the material is metal</p>	<p>Pass</p>

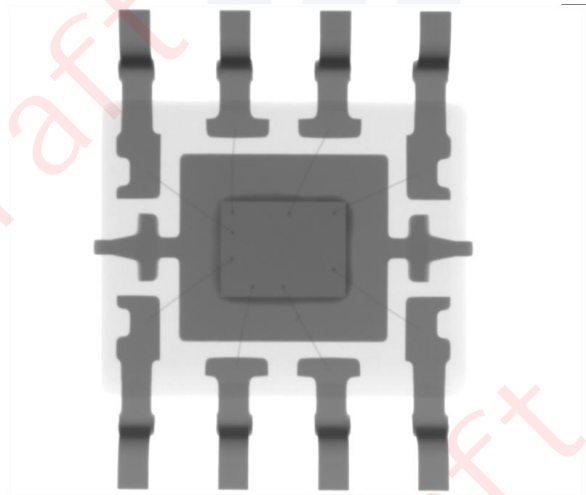
Top	Bottom
	
#1-Top view-All	#1-Side view-All
	
#2-Top view-All	#2-Side view-All



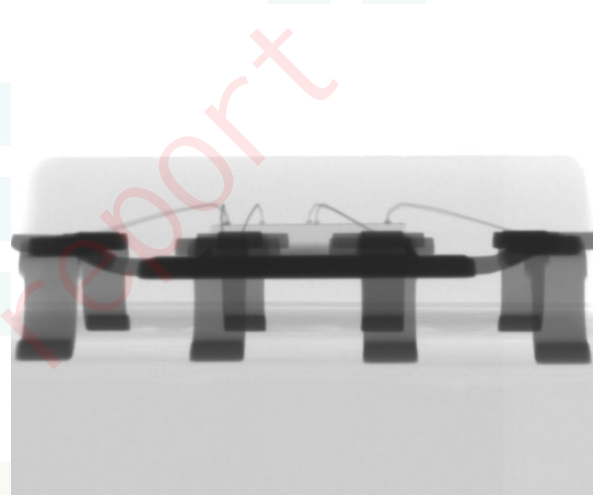
#3-Top view-All



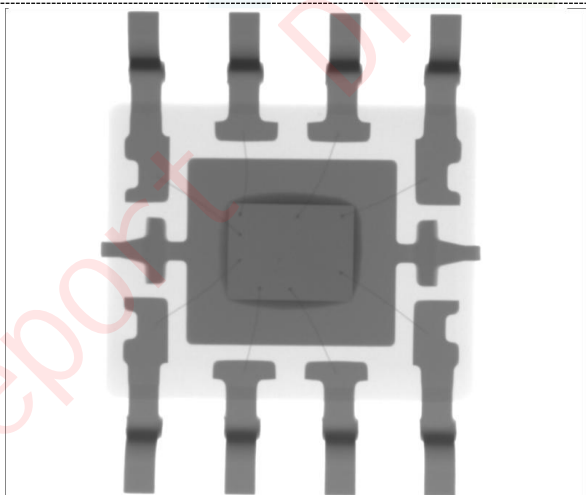
#3-Side view-All



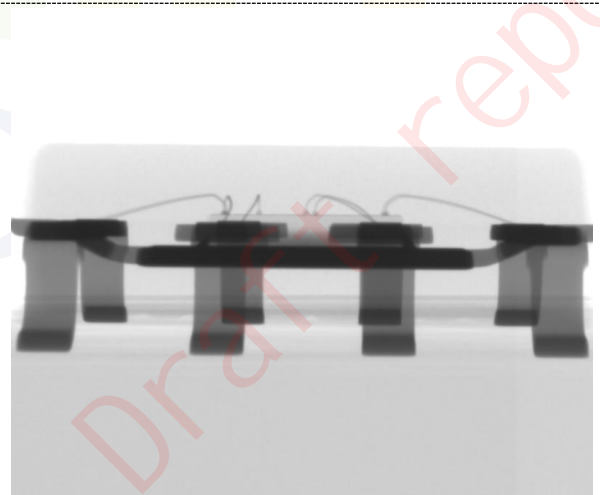
#4-Top view-All



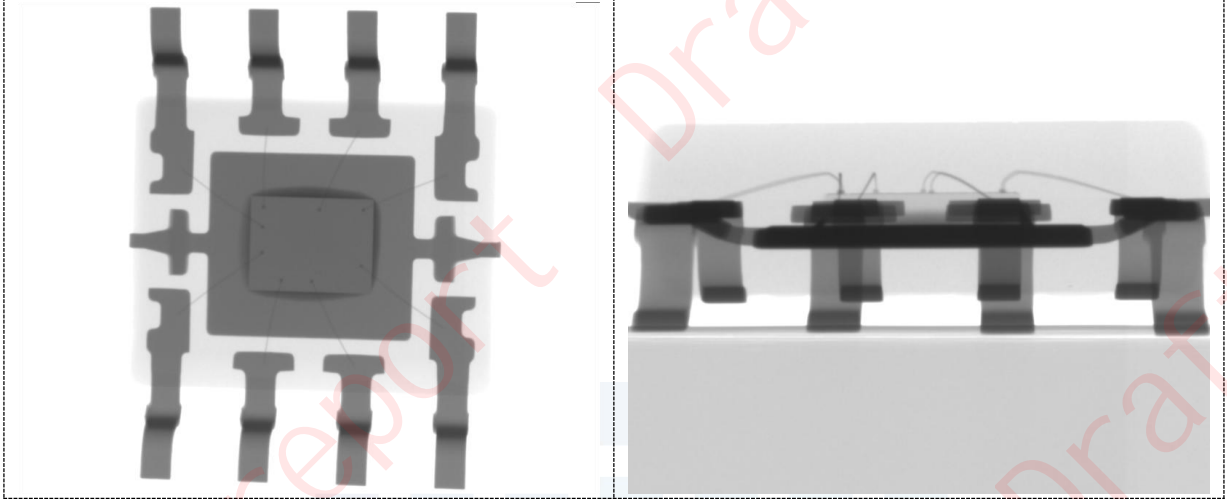
#4-Side view-All



#5-Top view-All



#5-Side view-All



-End of Report-

Disclaimer

1. The test report is invalid without the stamp of “company report seal” and “cross-page seal”.
2. The copy of the test report is invalid without the stamp of “company report seal” and “cross-page seal”.
3. The test report is invalid without the signatures of operator, supervisor and manager.
4. A modified or partial copy of the test report is invalid.
5. When there is disagreement with the test report, please submit the issue to us within 15 days from the date of receipt. Overdue information will not be accepted.
6. The test report is only reflective of the test results of testing samples, not of the quality of batch products.
7. The * indicates subcontract test data.
8. The report is stamped with the CMA mark, indicating that the test items are within the scope of qualification recognition; No CMA mark is stamped, indicating that some/all of the test items are not within the scope of CMA qualification, and the results are for internal use by the customer only.



CXOLab WeChat official account

Tel: 0755-83762185 **Email:** engineer@iclabcn.com

Website: <https://www.iclabcn.com>

Add: F/r 2nd, Building A, Yingdafeng Industrial Park, No.393, Jihua Rd.,
Longgang Dist., Shenzhen, China